

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SPECIFICATION

PART NO.: MTBL2410-G-A

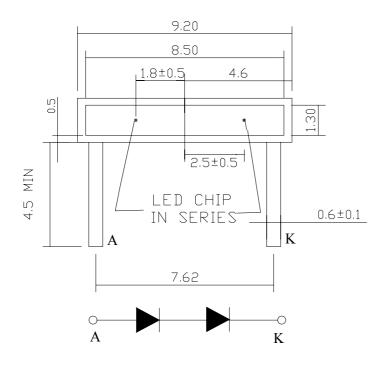
1.9 x 9.2mm SIDE VIEW LAMP

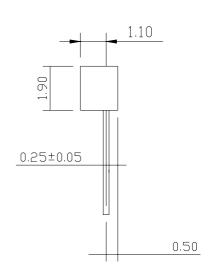






Package Dimensions





Notes:

- 1. ALL DIMENSIONS ARE IN mm.
- 2. TOLERANCE IS ± 0.25 mm UNLESS OTHERWISE NOTED.

Description

	LED Chip			
Part No.	Material	Emitting Color	Lens Color	
MTBL2410-G-A	GaP/GaP	Green	Green Clear	

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Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Unit
Power Dissipation	PD	156	mW
Reverse Voltage	VR	10	V
D.C. Forward Current	If	30	mA
Peak Current(1/10Duty Cycle,0.1ms Pulse Width.)	If(Peak)	100	mA
Operating Temperature Range	Topr.	-25 to +85	°C
Storage Temperature Range	Tstg.	-40 to +100	°C
Lead Soldering Temp. (1.6mm from body) for 5 seconds.		260	°C

Electrical and Optical Characteristics:

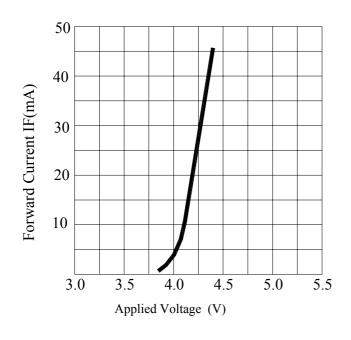
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Luminous Intensity	Iv	If=20mA	13.5	25		mcd
Forward Voltage	Vf	If=20mA		4.2	5.2	V
Peak Wavelength	λΡ	If=20mA		567		nm
Dominant Wavelength	λD	If=20mA		572		nm
Reverse Current	Ir	Vr=10V			100	μΑ
Viewing Angle	2θ 1/2	If=20mA		50		deg
Spectrum Line Halfwidth	Δλ	If=20mA		30		nm

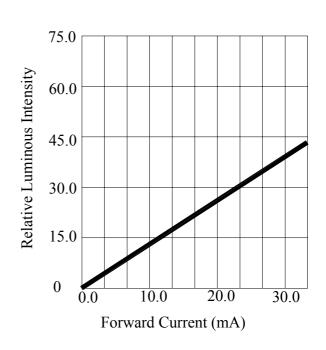
NOTE: THE DATAS TESTED BY IS TESTER

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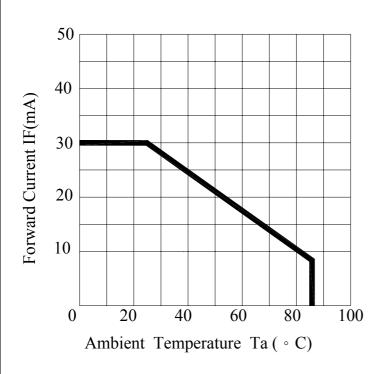
Typical Electrical/Optical Characteristic Curves (25°C Ambient Temperature Unless Otherwise Noted)

MTBL2410-G-A

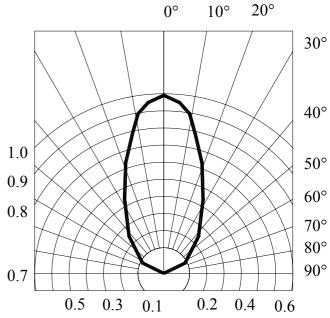




Forward Current VS. Applied Voltage



Forward Current VS. Luminous Intensity



Ambient Temperature vs. Forward Current

Radiation Diagram

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PRECAUTION IN USE

Storage

Recommended storage environment

Temperature: $5^{\circ}\text{C} \sim 30^{\circ}\text{C} (41^{\circ}\text{F} \sim 86^{\circ}\text{F})$

Humidity: 60% RH Max.

Use within 3 days after opening of sealed vapor/ESD barrier bags.

Fold the opened bag firmly and keep in dry environment.

Soldering

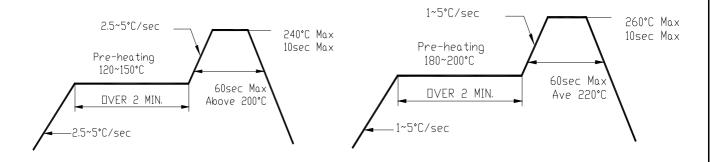
	Reflow So Idering	5	Hand S	oldering
Pre-heat Pre-heat time Peak temperature Soldering time Condition	Lead Solder 120~150°C 120sec Max 240°C Max 10sec Max refer to Temperature- profile 1	Lead – free Solder 180~200°C 120sec Max 260°C Max 10sec Max refer to Temperature- profile 2	Temperature Soldering time	350°C Max 3sec Max (one time only)

^{*}After reflow soldering rapid cooling should be avoided.

[Temperature-profile (Surface of circuit board)] Use the conditions shown to the under figure.

<1: Lead Solder >

<2: Lead-free Solder >



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